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PMP10188 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C2, C3	2	4.7uF	GRM32ER71H475KA88L	MuRata	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X7R, 1210	1210
2	C4, C5	2	0.1uF	GCM188R71H104KA57D	MuRata	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
3	C6	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01 μF, 50 V, +/- 10%, X7R, 0603	0603
4	C7	1	39pF	GRM1885C1H390JA01D	MuRata	CAP, CERM, 39 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
5	C8, C9	2	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 μF, 25 V, +/- 10%, X7R, 1210	1210
6	D1	1	40V	B340-13-F	Diodes Inc.	Diode, Schottky, 40 V, 3 A, SMC	SMC
7	J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
8	JP1	1		61300211121	Wurth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1,
							TH
9	L1	1	33uH	MSS1278-333MLB		Inductor, Shielded Drum Core, Ferrite, 33 µH, 3.1 A, 0.06 ohm, SMD	MSS1278
10	R1	1	15.8k	CRCW060315K8FKEA		RES, 15.8 k, 1%, 0.1 W, 0603	0603
11	R2	1	174k	CRCW0603174KFKEA		RES, 174 k, 1%, 0.1 W, 0603	0603
12	R3	1	280k	CRCW0603280KFKEA	Vishay-Dale	RES, 280 k, 1%, 0.1 W, 0603	0603
13	R4	1	14.0k	CRCW060314K0FKEA	Vishay-Dale	RES, 14.0 k, 1%, 0.1 W, 0603	0603
14	R5	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
15	R6	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
16	R7	1	6.34k	CRCW06036K34FKEA	Vishay-Dale	RES, 6.34 k, 1%, 0.1 W, 0603	0603
17	TP1, TP5, TP7	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
18	TP2, TP8	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
19	TP3, TP4, TP6	3	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
20	U1	1		TPS54260DGQ		Buck Inverting Buck-Boost Step Down Regulator with 3.5 to 60 V Input and 0.8 to 58 V Output, -40 to 150 degC, 10-Pin MSOP-PowerPAD (DGQ), Green (RoHS & no Sb/Br)	DGQ0010D

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